

REMARKS

In order to expedite the prosecution of the present application and more particularly point out and distinctly claim the subject matter which Applicants regard as the invention, Claim 10 has been amended to state that the thermoplastic resin consists of a blend of (1) a polyamide, (2) a styrene polymer selected from the group consisting of high-impact polystyrene, an acrylonitrile-butadiene-styrene copolymer, an acrylonitrile-styrene copolymer and a styrene-butadiene copolymer and (3) a copolymer of a carboxy group-containing unsaturated compound and styrene. No new matter has been added.

Claims 10-15, 19, 21 and 22 have been rejected under 35 USC 112, second paragraph, as being indefinite. Particularly speaking, the Examiner states that it is not clear what is meant by "metalized molded product". Applicant respectfully traverses this ground of rejection as Claim 10 clearly recites that the metalized molded product comprises a molded product having a metal plating provided thereon. As such, it is respectfully submitted that the currently presented claims clearly meet the requirements of 35 USC 112.

Claims 10-12 and 14 have been rejected under 35 USC 102(e) as being anticipated by Tamura. Claims 10, 11, 14 and 15 have been rejected under 35 USC 102(e) as being anticipated by Koichi. Claims 10, 11 and 14 have been rejected under 35 USC 103(a) as being unpatentable over Ichikawa. Claims 10-14, 19 and 21 have been rejected under 35 USC 103(a) as being unpatentable over Umetsu. Claims 10-12, 14 and 15 have been rejected under 35 USC 103(a) as being unpatentable over Hironaka in view of Kosaka. Claims 13, 19, 21 and 22 have been rejected under 35 USC 103(a) as being unpatentable over Hironaka in view of Kosaka and further in view of Umetsu. Applicant respectfully traverses these grounds of rejection and urges reconsideration in light of the following comments.

At the outset, Applicant wishes to point out that Tamura and Koichi are not available as prior art against the present application as the present application has a foreign priority date before the filing date of the Tamura reference and the publication date of the Koichi reference.

The presently claimed invention is directed to a metalized molded product which comprises the molded product being made of a thermoplastic resin composition comprising 90-30% by weight of (A) a thermoplastic resin consisting of a blend of (1) a polyamide, (2) a styrene polymer selected from the group consisting of high-impact polystyrene, an acrylonitrile-butadiene-styrene copolymer, an acrylonitrile-styrene copolymer and a styrene-butadiene copolymer and (3) a copolymer of a carboxy group-containing unsaturated compound and styrene, 5-60% by weight of (B) a fibrous filler and 5-60% by weight of (C) a whisker and a metal plating provided on the molded product.

The present invention is based on the discovery that the incorporation of a copolymer of a carboxy group-containing unsaturated compound and styrene into a thermoplastic resin composition also containing a polyamide and a styrene polymer selected from the group consisting of a high-impact polystyrene, an acrylonitrile-butadiene-styrene copolymer and an acrylonitrile-styrene copolymer improves the mechanical properties of the thermoplastic resin composition due to improving the compatibility between the polyamide and the styrene polymer. It is respectfully submitted that the prior art references cited by the Examiner do not disclose the presently claimed invention.

None of the references cited by the Examiner speak to the criticality of the thermoplastic resin composition consisting of a blend of (1) a polyamide, (2) a styrene polymer selected from the group consisting of high-impact polystyrene, an acrylonitrile-butadiene-styrene copolymer, an acrylonitrile-styrene copolymer and a styrene-butadiene copolymer and (3) a copolymer of a carboxy group-containing unsaturated compound

and styrene. That is, the thermoplastic resin of Tamura et al includes linear polymers formed by an additional polymerization reaction, such as polyethylene, polystyrene and polyvinyl chloride and polycondensates of difunctional monomers, such as polyesters and nylons. Specific examples include a polyarylene sulfide, a syndiotactic polystyrene, nylon 66, nylon 6, polyethylene terephthalate, polybutylene terephthalate, and acrylic resin and an acrylic-styrene resin. This reference discloses that the resins can be used either singly or in combination with a polyarylene sulfide and a syndiotactic polystyrene being especially preferable.

In the Koichi reference, the thermoplastic resins are disclosed as being a rubber consolidation styrene resin, such as a HIPS resin, ABS system resin, AES system resin, AAS system resin and MBS system resin, polycarbonate resin, polybutylene terephthalate resin, polyethylene terephthalate resin, polyamide resin, polypropylene resin, polyphenylene oxide resin, polyphenylene sulfide resin, etc.

The thermoplastic resin composition of Ichikawa et al may be an aromatic polyester, such as polyphenylene ether, denatured polyphenylene ether blended with polystyrene, polyethylene terephthalate, polybutylene terephthalate or polybutylene naphthalate, polyphenylene sulfide, polyetherimide, polyether ether ketone, a thermoplastic polyamide such as nylon 6, nylon 66, nylon 46, aromatic nylon or a copolymer of aromatic nylon and nylon 66, polysulfone, polyarylsulfone, polyethersulfone, or polythioethersulfone.

The thermoplastic resin composition of Umetsu et al comprises a semi-aromatic liquid-crystalline polyester and/or a semi-aromatic liquid-crystalline polyester-amide.

The thermoplastic resin composition in Hironaka includes general-purpose plastics such as polyethylene, polypropylene, ABS and polystyrene, engineering plastics such as aromatic polyesters, aromatic polycarbonates, polyamides, polyoxymethylene and modified polyphenylene ethers, super

engineering plastics such as aromatic polyamides, PPS and liquid crystal polymers.

The Kosaka reference has been cited by the Examiner as showing the interchangeability of engineering plastics such as polycarbonates, polyamides, polyacetals, polyethylene terephthalates, modified polyphenylene ethers, polysulfones and polyethersulfones with polyarylene sulfide resin compositions.

As discussed previously, none of the references cited by the Examiner disclose the criticality of a thermoplastic resin composition consisting of a blend of (1) a polyamide, (2) a polystyrene polymer selected from the group consisting of high-impact polystyrene, an acrylonitrile-butadiene-styrene copolymer, an acrylonitrile-styrene copolymer and a styrene-butadiene copolymer and (3) a copolymer of a carboxy group-containing unsaturated compound and styrene.

In order to establish the criticality of the presently claimed components of the thermoplastic resin composition, the Applicant is enclosing herewith a Declaration Under 37 CFR 1.132 in which the present inventor prepares a comparative composition which is to be compared directly to the composition of the present invention shown as Example 3 in the present specification. The composition of Comparative Example 7 in the enclosed Declaration is identical to the composition of Example 3 in the present specification except that instead of 6 parts by weight of a copolymer of a carboxy group-containing unsaturated compound and styrene, 12 parts by weight of an ABS resin is used. As shown by the results contained in the enclosed Declaration Under 37 CFR 1.132 and the results for Example 3 contained in the present specification, the comparative composition was inferior with respect to Izod impact strength and fluidity. This is clearly unexpected in light of the prior art cited by the Examiner and establishes the patentability of the presently claimed invention thereover.

The Examiner is respectfully requested to reconsider the present application and to pass it to issue.

Respectfully submitted,


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Encl: Declaration Under 37 CFR 1.132
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